IEEE Journal on Flexible Electronics

Call for Papers

Special Issue on *Selected Papers from the 8th IEEE International Flexible Electronics Technology Conference* (IFETC) 2026

The scope of this Special Journal Issue (SI) includes publication of a selected number of high-quality reviewed IFETC 2026 presented papers on a broad range of flexible/printable electronics device/manufacturing-related topics including sensors, displays, and in general large area flexible electronics systems. The authors of the selected papers, as notified by the conference technical program committee, are invited to submit an extended version of IFETC 2026 presented papers for consideration of publication in the proposed J-FLEX SI. All such submissions will comply with J-FLEX author-guidelines and be subjected to the standard IEEE and J-FLEX peer review process and publication policy.

Topics

- All areas of Flexible/Printable Electronics
- Stretchable/Shrinkable Sensors and Electronics
- Hybrid Systems-in-Foil
- Biomedical sensing devices
- Electronic textile/paper/skin
- Flexible/Printable Electronics in context with Circular Economy
- Organic/Inorganic/Hybrid Flexible Sensors and Electronics
- Flexible and Printable batteries and energy harvesters
- Wearable sensors
- Sensors for health monitoring
- Printable displays, lighting sources
- Packaging
- Smart tags, RFID tags, etc.
- Modeling of printable sensors
- Manufacturing Techniques (including Printing)
- Emerging Materials for Flexible and Printable Systems
- 3D printing

Important dates

October 5th 2026:	Call for Papers
December 18th 2026:	Deadline for Paper Submission
Jan 31st 2027:	Completion of First Review
Feb 28th 2027:	Completion of Final Review
March 31st 2027:	Publication

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Submission and Peer Review of Papers

All papers shall undergo the standard IEEE J-FLEX peer-review process. Manuscripts must be submitted online, via the *IEEE Journal on Flexible Electronics Author Portal*, see https://ieee.atyponrex.com/journal/jflex. When submitting, please indicate in the "Manuscript Type" roll down menu, and also by e-mail to Namrata Rastogi, namrata.rastogi@ieee.org, that the paper is intended for the **"Post-IFETC-2026"** Special Issue. Authors are particularly encouraged to **suggest names of potential reviewers** for their manuscripts in the space provided for these recommendations in *Manuscript Central.* For manuscript preparation and submission, please follow the guidelines in the *Information for Authors* at the IEEE J-FLEX web page, https://ieee-jflex.org/guidelines-for-authors/.

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